DIODES INCORPORATED

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PERICOM®

PI3B3244

## 3.3V, Hot Insertion, 8-Bit, 2-Port NanoSwitch

Features

→ Near-Zero propagation delay

→ 5-ohm switches connect inputs to outputs

→ Fast Switching Speed: 4.5ns (max.)

→ Ultra-Low Quiescent Power (0.2µA Typical)

  □ Ideally suited for notebook applications

→ Packaging (Pb-free & Green):

  □ 20-pin 150-mil wide plastic QSOP (Q)

 □ 20-pin 173-mil wide plastic TSSOP (L)

Description

Pericom Semiconductor's PI3B series of logic circuits are produced using the Company's advanced sub-micron CMOS technology, achieving industry leading performance.

The PI3B3244 features a set of 3.3V 8-bit bus switches, which is pinout and function compatible with the P74FCT244T, 74F244, and 74ALS/AS/LS2448-bit drivers. Two enable signals ($\overline{BEn}$) turn the switches on similar to the enable signals of the 244. The bus switch create no additional propagation delay or ground bounce noise.

Block Diagram
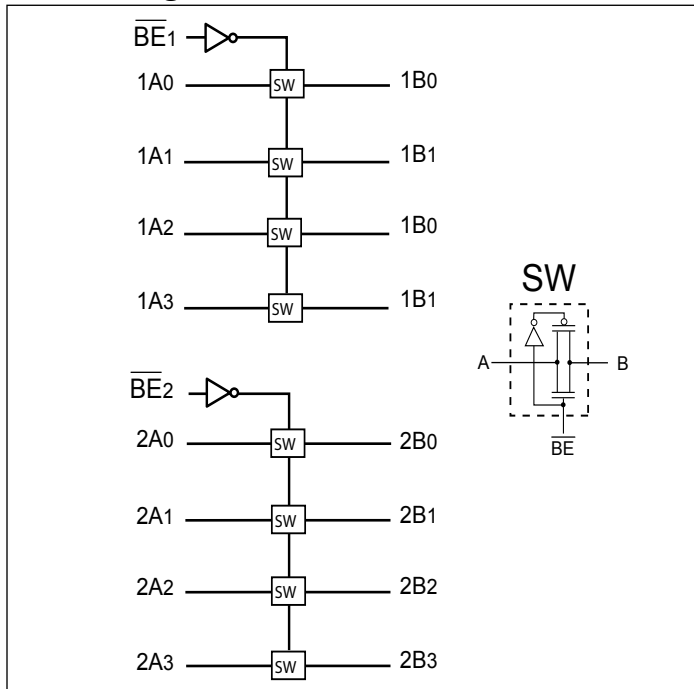
Pin Configuration
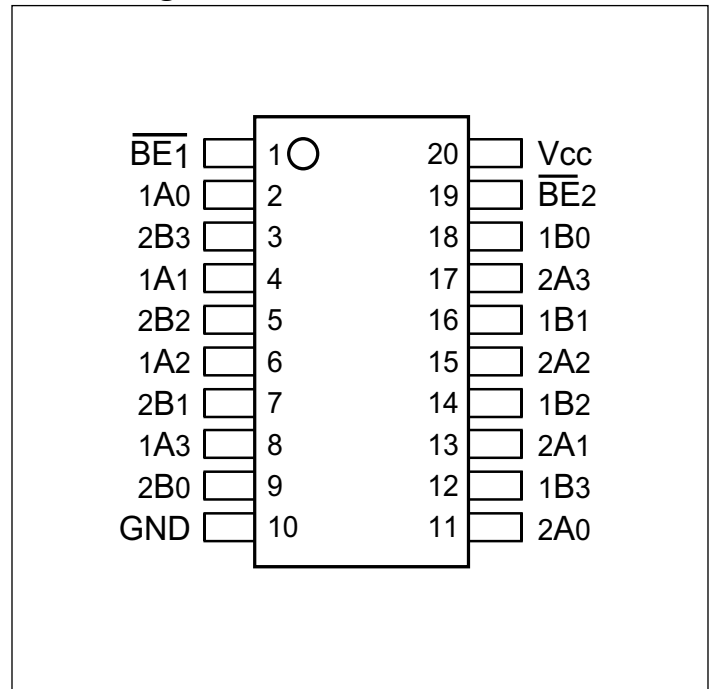
Pin Description

Pin Name	Description
$\overline{BEn}$	Bus Enable Input (Active LOW)
A0-7	Bus A
B0-7	Bus B
GND	Ground
V_{CC}	Power

Truth Table[1]

$\overline{BE1}$	$\overline{BE2}$	1A, 1B	2A, 2B
H	H	Disconnect	Disconnect
L	H	1A = 1B	Disconnect
H	L	Disconnect	2A = 2B
L	L	1A = 1B	2A = 2B

Note:

1. H = High Voltage Level, L = Low Voltage Level

Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

Storage Temperature... −65°C to +150°C

Ambient Temperature with Power Applied .... −40°C to +85°C

Supply Voltage to Ground Potential................................. -0.5V to +4.6V

DC Input Voltage .... −0.5V to +4.6V

DC Output Current 120mA

Power Dissipation 0.5W

Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC Electrical Characteristics (Over the Operating Range, T_A = −40°C to +85°C, V_{CC} = 3.3V ±10%)

Parameters	Description	Test Conditions[1]	Min.	Typ.[2]	Max.	Units
V_{IH}	Input HIGH Voltage	Guaranteed Logic HIGH Level	2.0			V
V_{IL}	Input LOW Voltage	Guaranteed Logic LOW Level	-0.5		0.8	V
I_{IH}	Input HIGH Current	V_{CC} = Max., V_{IN} = V_{CC}			±1	μA
I_{IL}	Input LOW Current	V_{CC} = Max., V_{IN} = GND			±1	μA
I_{OZH}	High Impedance Output Current	$0 \leq I_N$, $Y_N \leq V_{CC}$			±1	μA
V_{IK}	Clamp Diode Voltage	V_{CC} = Min., I_{IN} = −18 mA			-1.2	V
R_{ON}	Switch On Resistance[3]	V_{CC} = Min., V_{IN} = 0.0V, I_{ON} = 48mA or 64mA		5	8	Ω
		V_{CC} = Min, V_{IN} = 2.4V, I_{ON} = 15mA		10	17	

Capacitance (T_A = 25°C, f = 1 MHz)

Parameters[1]	Description	Test Conditions	Typ.	Units
C_{IN}	Input Capacitance	V_{IN} = 0V	3.0	pF
C_{OFF}	A/B Capacitance, Switch Off	V_{IN} = 0V	8.0	pF
C_{ON}	A/B Capacitance, Switch On	V_{IN} = 0V	16.0	pF

Notes:

1. For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.

2. Typical values are at V_{CC} = 3.3V, T_A = 25°C ambient and maximum loading.

3. Measured by the voltage drop between A and B pin at indicated current through the switch. ON resistance is determined by the lower of the voltages on the two (A,B) pins.

4. This parameter is determined by device characterization but is not production tested.

Power Supply Characteristics

Parameters	Description	Test Conditions[1]		Min.	Typ. [2]	Max.	Units
I_{CC}	Quiescent Power Supply Current	V_{CC} = Max.	V_{IN} = GND or V_{CC}		0.1	3.0	µA
ΔI_{CC}	Supply Current per Input @ TTL HIGH	V_{CC} = Max.	V_{IN} = 3.0V[3]			750	µA

Notes:

1. For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device.

2. Typical values are at V_{CC} = 3.3V, +25°C ambient.

3. Per TTL driven input (control input only); A and B pins do not contribute to I_{CC}.

Switching Characteristics over Operating Range

Parameters	Description	Test Conditions[1]	Com.		Units
			Min.	Max.	
t_{PLH} t_{PHL}	Propagation Delay[2,3] Ax to Bx	CL = 50 pF RL = 500Ω		0.25	ns
t_{PZH} t_{PZL}	Bus Enable Time $\overline{BE}$ to Ax or Bx		1.0	4.0	
t_{PHZ} t_{PLZ}	Bus Disable Time $\overline{BE}$ to Ax or Bx		1.0	4.5	

Notes:

1. See test circuit and wave forms.

2. This parameter is guaranteed but not tested on Propagation Delays.

3. The bus switch contributes no propagational delay other than the RC delay of the On-Resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 0.25 ns for 50 pF load. Since this time constant is much smaller than the rise/fall times of typical driving signals, it adds very little propagational delay to the system. Propagational delay of the bus switch when used in a system is determined by the driving circuit on the driving side of the switch and its interaction with the load on the driven side.

Applications Information

Logic Inputs

The logic control inputs can be driven up to +3.6V regardless of the supply voltage. For example, given a + 3.3V supply, IN may be driven low to 0V and high to 3.6V. Driving IN Rail-to-Rail® minimizes power consumption.

Power-Supply Sequencing and Hot-Plug Information

Proper power-supply sequencing is recommended for all CMOS devices. Always apply V_{CC} and GND before applying signals to input/output or control pins.

Rail-to-Rail is a registeredtrademark of Nippon Motorola, Ltd.

Packaging Mechanical: 20-Pin QSOP (Q)

SYMBOLS	MIN.	NOM.	MAX.
A	–	–	0.069
A1	0.004	–	0.0098
A2	0.049	–	–
b	0.008	–	0.012
c	0.004	–	0.010
D	0.337	0.341	0.345
E	0.228	0.236	0.244
E1	0.150	0.154	0.158
e		0.025 BSC	
L	0.016	0.025	0.050
L1		0.041 REF	
θ°	0°	–	8°

UNIT : INCH

SEATING PLANE

DETAIL A

PERICOM
Enabling Serial Connectivity

	DATE: 03/24/16
DESCRIPTION: 20-Pin, 150mil Wide QSOP	
PACKAGE CODE: Q (Q20)	
DOCUMENT CONTROL #: PD-1202	REVISION: I

NOTES:
1. ALL DIMENSIONS IN INCH. ANGLES IN DEGREES.
2. JEDEC MO−137E
3. DIMENSIONS DOES NOT INCLUDE MOLD FLASH,
   PROTRUSIONS OR GATE BURRS.

16-0057

Packaging Mechanical: 20-Pin TSSOP (L)

SYMBOLS	MIN.	NOM.	MAX.
A	–	–	1.20
A1	0.05	–	0.15
A2	0.80	1.00	1.05
b	0.19	–	0.30
C	0.09	–	0.20
D	6.40	6.50	6.60
E1	4.30	4.40	4.50
E	6.20	6.40	6.60
e	0.65 BSC		
L1	1.00 REF		
L	0.45	0.60	0.75
S	0.20	–	–
θ	0°	–	8°

NOTES:
1. ALL DIMENSIONS IN MILLIMETERS. ANGLES IN DEGREES.
2. JEDEC MO−153F
3. DIMENSIONS DOES NOT INCLUDE MOLD FLASH,
   PROTRUSIONS OR GATE BURRS.

16-0074

DATE: 03/31/16

PERICOM
Enabling Serial Connectivity

DESCRIPTION: 20-Pin, 173mil Wide TSSOP

PACKAGE CODE: L (L20)

DOCUMENT CONTROL #: PD-1311   **REVISION: G**

Note: For latest package info, please check: http://www.pericom.com/support/packaging/packaging-mechanicals-and-thermal-characteristics/

Ordering Information

Ordering Code	Package Code	Package Type
PI3B3244QE	Q	20-Pin, 150mil Wide (QSOP)
PI3B3244QEX	Q	20-Pin, 150mil Wide (QSOP), Tape & Reel
PI3B3244LE	L	20-Pin, 173mil Wide (TSSOP)
PI3B3244LEX	L	20-Pin, 173mil Wide (TSSOP), Tape & Reel

1. Thermal characteristics can be found on the company web site at www.pericom.com/packaging/

2. E = Lead-free and Green

3. Adding X suffix = Tape/Reel